

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: A1911-01		DATE: 26-Nov-2019	MEANS OF DISTINGUISHING CHANGED DEVICES: ☒ Product Mark 2D barcode on product marking ☐ Back Mark ☐ Date Code ☐ Other
Product Affected: FCBGA53 and FCBGA253 (Refer to attachment II for affected part#)			
Date Effective: 26-Dec-2019			
Contact: IDT PCN DESK	Attachment: ☒ Yes ☐ No		
E-mail: idt-pcn@lm.renesas.com	Samples: Please contact your local sales representative for sample request.		

DESCRIPTION AND PURPOSE OF CHANGE:

- ☐ Die Technology
- ☐ Wafer Fabrication Process
- ☒ Assembly Process
- ☐ Equipment
- ☐ Material
- ☐ Testing
- ☐ Manufacturing Site
- ☐ Data Sheet
- ☐ Other

This notification is to advise our customers that IDT is adding 2D barcode on product marking to improve the traceability. The 2D barcode contains the wafer and substrate information.

There is no change to the moisture performance.

RELIABILITY/QUALIFICATION SUMMARY:

Not applicable

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____	☐ Approval for shipments prior to effective date.
Name/Date: _____	E-Mail Address: _____
Title: _____	Phone# /Fax# : _____

CUSTOMER COMMENTS:

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____ DATE: _____

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ATTACHMENT I - PCN # : A1911-01

PCN Type: Assembly Process

Data Sheet Change: None

No change in moisture sensitivity level (MSL)

Detail Of Change:

This notification is to advise our customers that IDT is adding 2D barcode on the product marking to improve traceability. The 2D barcode contains wafer and substrate information.

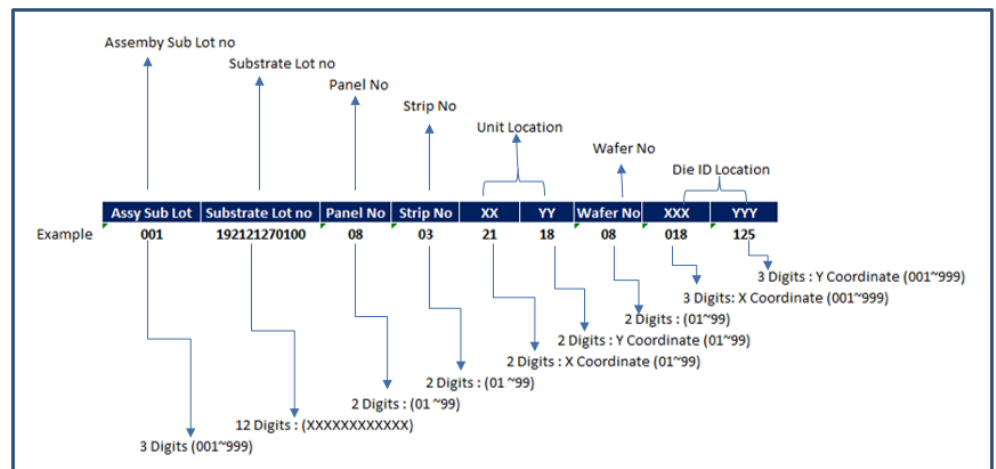
There is no change to the moisture performance.

2D Barcode Information

RCD: 13.5 x 8.0 mm



DB: 7.5 x 3.0 mm

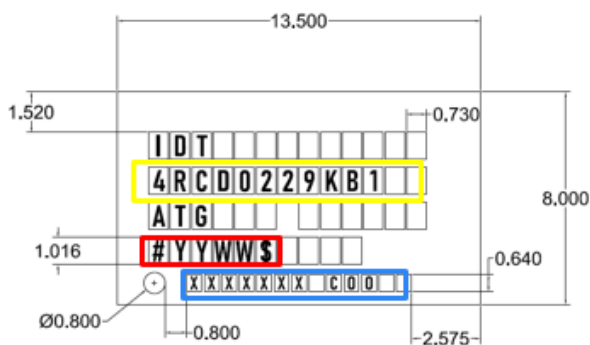


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ATTACHMENT I - PCN # : A1911-01

DDR4 RCD Marking Format and Dimension

CURRENT MARKING



NEW MARKING



4RCD0229KB1

Device info – Line 2

#YYWW\$

Device step, 4th line “#”

Subcon location 4th line “\$”

Date code is YYWW – 4th line

XXXXXXXXXXC000

Assembly lot no. – last line beside pin 1

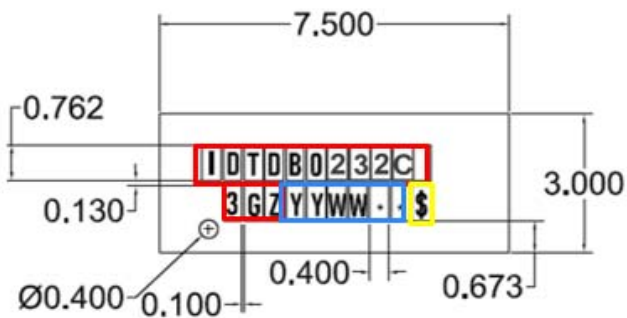
- Fixed Substrate level 2D ID Content
 - 17 digit max
 - Lot no (12) + PP + SS
- Combine Sublot + Substrate 2D ID info + Unit code + wafer and die ID and mark into IDT Unit
 - Total 31 digits
 - Assembly Sublot (3)
 - substrate Lot no (12)
 - Panel No PP(2)
 - Strip No SS(2)
 - Unit Location, XXYY(4)
 - Wafer ID WW(2)
 - Die Location XXXYYY (6)

PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT I - PCN # : A1911-01

DDR4 DB Marking Format and Dimension

CURRENT MARKING



DB0232

C3GZ

Device info is on line 1 & 2
Device Step is on line 2 "Z"

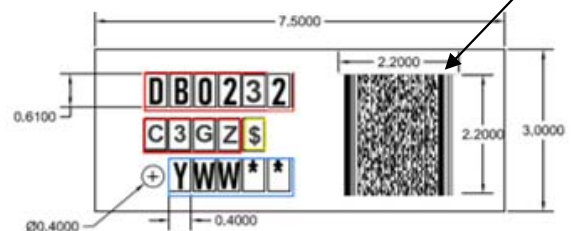
\$

Last character of line 2, "\$", subcon location

YWW**

3rd line, YWW, Date code
Assembly lot no 3rd line "***" – Lot Sequential code.

NEW MARKING



- Fixed Substrate level 2D ID Content
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 - Total 31 digits
 - Assembly Sublot (3)
 - substrate Lot no (12)
 - Panel No PP(2)
 - Strip No SS(2)
 - Unit Location, XXYY(4)
 - Wafer ID WW(2)
 - Die Location XXXYYY (6)

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ATTACHMENT II - PCN # : A1911-01

Affected Part Numbers

Part Number	Part Number	Part Number	Part Number
4DB0124KB0AVG8	4DB0232KC1AAVG	4RCD0124KC0ATGI	4RCD0232HDKC1ATG
4DB0124KB1AVG8/M	4DB0232KC1AAVG8	4RCD0124KC0ATGI8	4RCD0232HDKC1ATG8
4DB0226EMKB0AVG	4DB0232KC1AVG	4RCD0229EMKB1ATG	4RCD0232KC0ATG
4DB0226EMKB0AVG8	4DB0232KC1AVG/M	4RCD0229EMKB1ATG8	4RCD0232KC0ATG/M
4DB0226KA3AVG	4DB0232KC1AVG8	4RCD0229KB0ATG	4RCD0232KC0ATG8
4DB0226KA3AVG/M	4DB0232KC1AVG8/M	4RCD0229KB0ATG8	4RCD0232KC0ATG8/M
4DB0226KA3AVG8	4DB0232KC2AAVG	4RCD0229KB1ATG	4RCD0232KC1ATG
4DB0226KA3AVG8/M	4DB0232KC2AAVG8	4RCD0229KB1ATG/M	4RCD0232KC1ATG/M
4DB0226KB0AAVG	4DB0232KC2AVG	4RCD0229KB1ATG8	4RCD0232KC1ATG8
4DB0226KB0AVG	4DB0232KC2AVG/M	4RCD0229KB1ATG8/B	4RCD0232KC1ATG8/B
4DB0226KB0AVG/M	4DB0232KC2AVG8	4RCD0229KB1ATG8/M	4RCD0232KC1ATG8/M
4DB0226KB0AVG8	4DB0232KC2AVG8/M	4RCD0229KB1MATG	4RCD0232KC1ATGI
4DB0226KB0AVG8/M	4DB0232KD0AVG	4RCD0229KB1MATG8	4RCD0232KC1ATGI/M
4DB0226KB0BAVG	4DB0232KD0AVG8	4RCD0232EMKC0ATG	4RCD0232KC1ATGI8
4DB0226KB0MAVG	4DB0232KD1AVG	4RCD0232EMKC0ATG8	4RCD0232KC1ATGI8/M
4DB0226KB0MAVG8	4DB0232KD1AVG8	4RCD0232EMKC1ATG	4RCD0299EMKB1ATG
4DB0232EMKD1AVG	4RCD0124KC0ATG	4RCD0232EMKC1ATG/B	4RCD0299EMKB1ATG8
4DB0232EMKD1AVG8	4RCD0124KC0ATG8	4RCD0232EMKC1ATG8	
4DB0232KC0AVG	4RCD0124KC0ATG8/B	4RCD0232EMKC1ATG8/	
4DB0232KC0AVG8	4RCD0124KC0ATG8/M	4RCD0232EMKC1ATG8B	